



# HYDRO-X20

June 2007

**WATER SOLUBLE LIQUID FLUX**  
**Multicore Hydro-X/20 water soluble flux is formulated for use on electronic assemblies designed for water cleaning.**

- **Highly water soluble solder residues eliminates CFC usage**
- **No penetration of properly cured solder resists**
- **No solder balls on dry film resists**
- **Leaves boards very clean with no white residues after washing**
- **No offensive odour**
- **Minimal residues on clean boards which easily meet the requirements of MIL-P-28809A**

## APPLICATIONS

Multicore Hydro-X/20 Water Soluble Flux is formulated for use on electronic assemblies which have been designed for water cleaning and will therefore meet the demand for those fluxes whose residues need not be removed in CFC type cleaning solvents.

A number of safety features have been built into the formulation of Hydro-X/20, particularly the fact that residues after soldering do not create excessive foam in the washing water and can be considered safe for disposal.

## RECOMMENDED OPERATING CONDITIONS

**The Printed Circuit Board:** Multicore Hydro-X/20 is suitable for use on plain copper or tin-lead coated PCBs. It does not penetrate solder resists which have been properly cured. On dry film resists, such as Vacrel, there is no tendency to produce solder balls.

**Fluxing:** Multicore Hydro-X/20 has been formulated for use in automatic wave and drag soldering machines and is particularly suitable for use with foam units. The fine quality form generated produces a uniform coating of flux on the circuit boards.

**Flux Control:** Control of the flux concentration is achieved by measuring the temperature and the specific gravity of the flux.

A nomograph is available to show how these measurements are related to the corrective action needed.

**Preheating:** During preheating, the solvent blend used in Multicore Hydro-X/20 will not cause spattering to occur.

Solders: Multicore Hydro-X/20 can be used with all standard solder alloys.

Multicore Hydro-X water soluble flux cored solder wires and solder creams are also available.

**Cleaning:** It is essential that the residues from soldering with Multicore Hydro-X/20 flux be removed as soon as possible after soldering. Multicore Hydro-X/20 flux residues may be readily cleaned in conventional equipment using water. The flux residues do not cause excessive foam in the washing water and present no special hazard during disposal.

Properly processed and cleaned boards soldered using Multicore Hydro-X/20 easily meet the ionic contamination requirements of MIL-P-28809A. It is recommended that samples from production are regularly checked to see that the cleaning process is operating effectively.

## TECHNICAL SPECIFICATION

A full description of the methods of test and detailed test results are available on request.

General Properties	Hydro-X/20
Colour	Green
Solids content	20 ± 1% w/w
Specific gravity at 25°C (77°F)	0.874 ± 0.003
Halide content (as % chloride)	0.98 ± 0.02
Flash point (Abel)	12°C (53°F)
Acid value (mg KOH/g)	24 ± 2
Ph	3.0
Freeze-thaw stability	Will not separate at temperatures as low as -20°C
Thinners	PC70i

Other concentrations of Multicore Hydro-X/20 may be available for special applications.

## SPECIAL PROPERTIES

Multicore Hydro-X/20 will solder copper, brass, nickel and mild steel efficiently. It will not spatter during preheating and soldering.

The soldering residues from Hydro-X/20 are readily washed off to leave a surface which easily meets the requirements of MIL-P-28809A ionic contamination test.

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 TECHNICAL SERVICE FOR ASSISTANCE AND RECOMMENDATIONS ON SPECIFICATIONS FOR IS PRODUCT.

**GENERAL INFORMATION**

**For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).**

**Note**

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**Americas**

Henkel Corporation  
15350 Barranca Parkway  
Irvine, CA 92618 U.S.A.  
949.789.2500

**Europe**

Henkel Loctite Adhesives Ltd  
Technologies House, Wood Lane End  
Hemel Hempstead  
Hertfordshire HP2 4RQ, United Kingdom  
+44 (0) 1442 278 000

**Asia**

Henkel Loctite (China) Co. Ltd  
No. 90 Zhujiang Road  
Yantai Development Zone  
Shandong, China 264006  
+86 535 6399820

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